

# Wafer Level Packaging Market: Global Industry Trends, Share, Size, Growth, Opportunity and Forecast 2023-2028

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## Abstracts

### Market Overview:

The global wafer level packaging market size reached US\$ 4.8 Billion in 2022. Looking forward, IMARC Group expects the market to reach US\$ 13.2 Billion by 2028, exhibiting a growth rate (CAGR) of 18.3% during 2023-2028.

The wafer-level packaging (WLP) refers to a packaging solution used for adding a protective layer of electronic connections and integrated circuits (ICs). It is used for devices, such as microphones, pressure sensors, accelerometers, gyroscopes, capacitors, resistors and transistors. Some of the commonly used WLP integration types include fan-out (FO), fan-in (FI), flip-chip, 3D FOWLP. These solutions are used at the wafer-level of the device, instead of dicing the wafer into the individual die and packaging them. This offers various benefits, such as a reduction in the size of the wafer chips, streamlining of the manufacturing processes and improvements in chip functionalities. The ultrathin wafers also provide improved heat dissipation and performance, form factor reduction and minimal power consumption.

Significant growth in the electronics industry across the globe represents one of the key factors creating a positive outlook on the market growth. Furthermore, the increasing requirement for more compact and faster consumer electronics is also driving the market growth. This has also enhanced the overall demand for cost-effective and high-performance packaging solutions for enhanced mechanical protection, structural support and extended battery life of the devices. Additionally, various technological advancements, such as the integration of connected devices with the Internet of Things (IoT), are acting as other growth-inducing factors. For instance, WLP is widely used for

the manufacturing of radar systems in self-driving automobiles. It is also used in the healthcare sector for the production of various wearable devices. Other factors, including increasing circuit miniaturization in microelectronic devices, along with extensive research and development (R&D) activities, are anticipated to drive the market further.

#### Key Market Segmentation:

IMARC Group provides an analysis of the key trends in each sub-segment of the global wafer level packaging market report, along with forecasts at the global, regional and country level from 2023-2028. Our report has categorized the market based on packaging technology and end use industry.

#### Breakup by Packaging Technology:

- 3D TSV WLP
- 2.5D TSV WLP
- WLCSP
- Nano WLP
- Others

#### Breakup by End Use Industry:

- Aerospace and Defense
- Consumer Electronics
- IT & Telecommunication
- Healthcare
- Automotive
- Others

#### Breakup by Region:

- North America
  - United States
  - Canada

## Asia-Pacific

- China
- Japan
- India
- South Korea
- Australia
- Indonesia
- Others

## Europe

- Germany
- France
- United Kingdom
- Italy
- Spain
- Russia
- Others

## Latin America

- Brazil
- Mexico
- Others

## Middle East and Africa

### Competitive Landscape:

The competitive landscape of the industry has also been examined along with the profiles of the key players being Amkor Technology Inc., China Wafer Level CSP Co. Ltd., Chipbond Technology Corporation, Deca Technologies Inc. (Infineon Technologies AG), Fujitsu Limited, IQE PLC, JCET Group Co. Ltd., Siliconware Precision Industries Co. Ltd. (Advanced Semiconductor Engineering Inc.), Tokyo Electron Ltd. and Toshiba Corporation.

### Key Questions Answered in This Report:

How has the global wafer level packaging market performed so far and how will it perform in the coming years?

What has been the impact of COVID-19 on the global wafer level packaging market?

What are the key regional markets?

What is the breakup of the market based on the packaging type?

What is the breakup of the market based on the end use industry?

What are the various stages in the value chain of the industry?

What are the key driving factors and challenges in the industry?

What is the structure of the global wafer level packaging market and who are the key players?

What is the degree of competition in the industry?

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